Title: Review of Photon Counters

Speakers: Karl Berggren, Joshua Bienfang

**Collection/Series:** Future Prospects of Intensity Interferometry

**Subject:** Cosmology

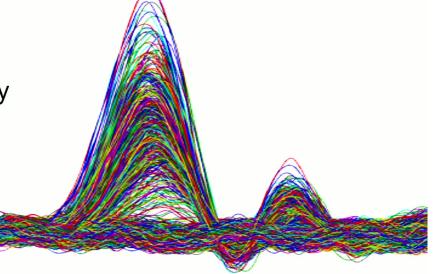
**Date:** October 31, 2024 - 9:00 AM

**URL:** https://pirsa.org/24100100

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# Review of Single-Photon Avalanche Diodes

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Workshop on Intensity Interferometry for Astronomy Perimeter Institute, Waterloo, Ontario, 10/31/2024

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### Outline

- SPAD Introduction and Fundamentals
- Design, Internal Behavior and External Characteristics
- Types of SPADs and Quenching Circuits
- Conclusions

#### **Executive Summary**

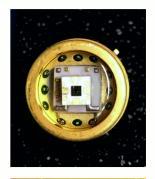
- 1. SPADs offer high performance single-photon detection in every\* metric.
- 2. But not all metrics are achieved in a single device; there are always tradeoffs.
- 3. The tradeoffs can be strong, but SWAP and fab capabilities often makes up for them.

\*caveats about wavelength range and perhaps ultra-low noise



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## Single-Photon Avalanche Diodes (SPADs)



Avalanche diodes voltage reverse biased above breakdown

→ a single photogenerated electron-hole pair can trigger an exponential growth in current through runaway impact ionization.





- · Low cost, compact, low power
- Room temperature (... well, TE cooled to reduce dark counts)
- Diameters from < 10 μm to 500 μm
- System detection efficiencies > 85% in Si, > 50% in InGaAs
- Dark count rates can be < 10 s<sup>-1</sup> in Si, < 10<sup>3</sup> s<sup>-1</sup> in InGaAs
- FWHM jitter < 10 ps in small area devices
- Max count rates > 10<sup>8</sup> s<sup>-1</sup> in Si and gated InGaAs
- CMOS compatible: large arrays, integration, 3D ToF imagers



Afterpulsing << 1% in Si, much worse in InGaAs (unless gated)</li>











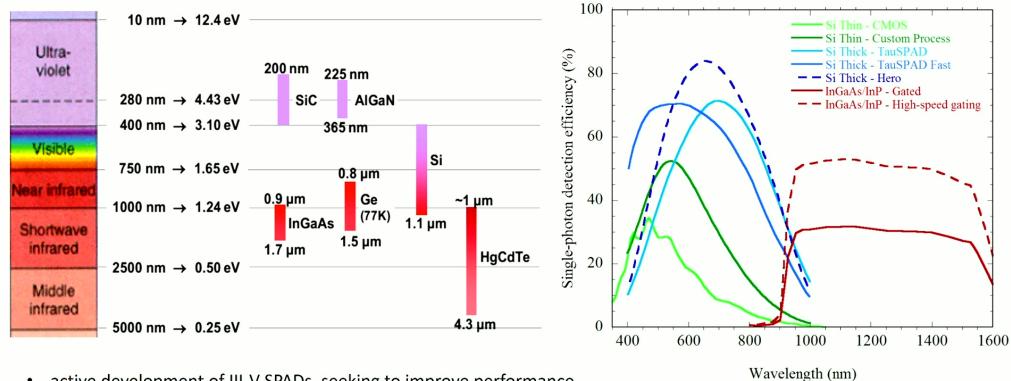




Disclaimer: The mention of any commercial product does not imply recommendation or endorsement by the U.S. National Institute of Standards and Technology. 3

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### Semiconductor SPAD Materials



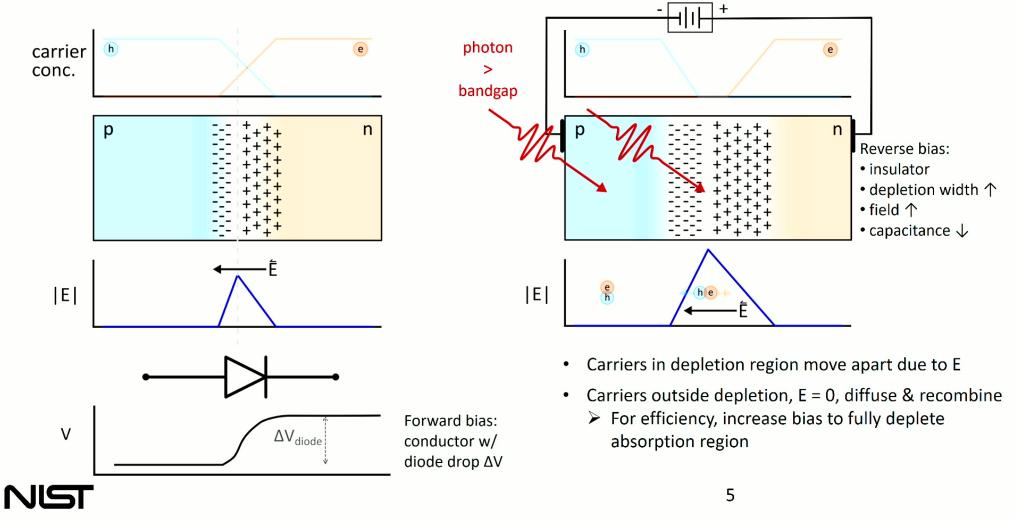
- active development of III-V SPADs, seeking to improve performance
- active development of Si SPAD arrays with greater functionality and performance (e.g. gated arrays, individually controlled)
- nascent UV SPAD development



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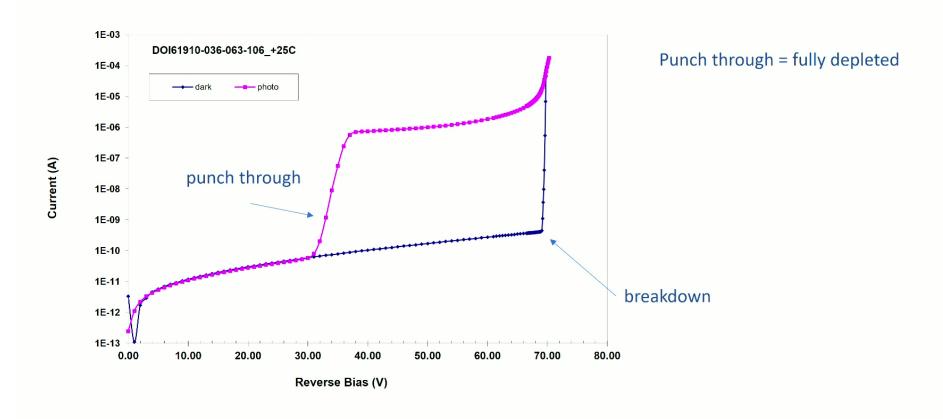
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### Si Avalanche Photodiode Fundamentals



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### SPAD I-V Curve





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### Si Linear Avalanche Photodiode Fundamentals

- With high E, carrier energy > Si bandgap between collisions → Impact Ionization, liberating another carrier (pair)
  - · Internal gain mechanism, or "avalanche"
- A toy model: single-photon generates e-h pair. Say the probability of ionization through device is  $\alpha$ . The mean gain is

$$M = 1 + \alpha + \alpha^{2} + \alpha^{3} + \dots = \frac{1}{1 - \alpha}$$
$$\alpha \to 1, M \to meaningless$$

- Runaway impact ionization when the field is above breakdown ("Geiger mode;" gain is undefined)
- Breakdown depends on doping/field profile, but a \*very\* rough figure of merit is 100 V for 10 μm thickness.
- Avalanche gain is a highly stochastic process and, when starting from a single e-h pair, can self-terminate
  - energy losses to lattice, probabilistic ionization → fluctuating gain gives large "excess noise factor"
  - no "linear-mode" photon counting

IEEE TRANSACTIONS ON ELECTRON DEVICES, VOL. ED-19, NO. 6, JUNE 1972

The Distribution of Gains in Uniformly Multiplying Avalanche Photodiodes: Theory

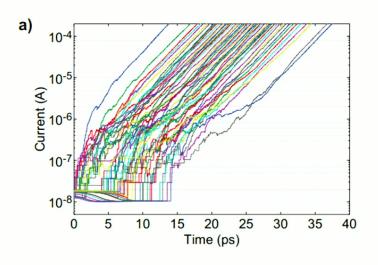
ROBERT J. McINTYRE, SENIOR MEMBER, IEEE

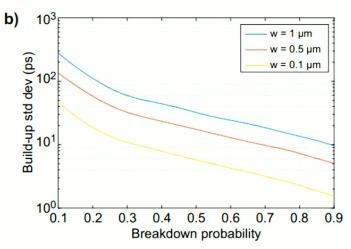
 → Result: To reduce excess noise it is better to have one type of carrier do all the ionizing
 - Triggering probability



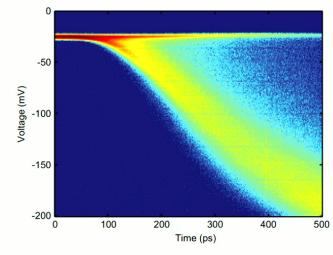
7

### Models of Avalanche Growth





- Models are for qualitative understanding; not quantitatively predictive
- Stochastic nature of avalanche growth contributes to triggering efficiency and timing resolution
  - Thinner avalanche regions improve timing resolution





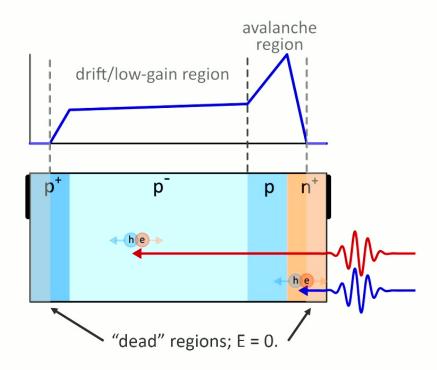
[Acconcia et al., Optics Express 31, 33963 (2023)]

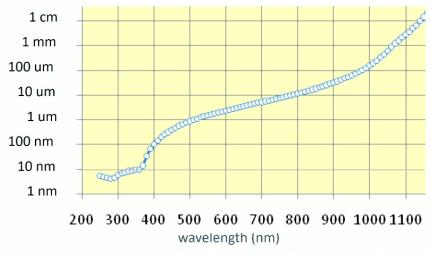
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### Si SPAD Fundamentals

- In Si,  $\alpha_{elec}$  is larger than  $\alpha_{hole}$
- Can achieve low k devices, where  $k=\alpha_{hole}/\alpha_{elec}$ , by having some multiplication throughout the device, but having the multiplication peak very close to the cathode where the hole density is low
  - The SLiK<sup>TM</sup> device;  $k \approx 0.002$

[Dautet et al., Appl. Opt. 32, 3894 (1993)]





 $[\mathsf{M.\,A.\,Green,\,Prog.\,Photovoltaics:\,Research\,and\,Applications\,\textbf{3},\,189\,(1995)}]$ 

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## Detection Efficiency: Thick Si SPAD

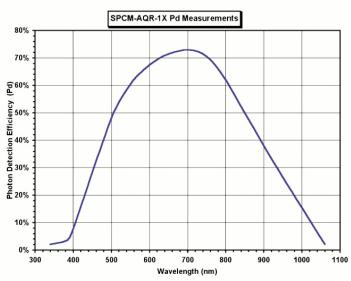
 $SDE = (1 - R_{in}) \times P_{abs} \times P_{trig}$ 

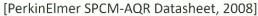
 $R_{in} \equiv optical \ reflection$ 

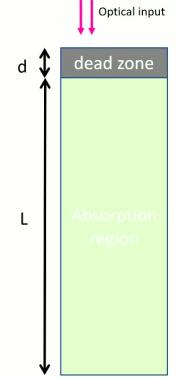
 $P_{abs} \equiv absorption prob.$ 

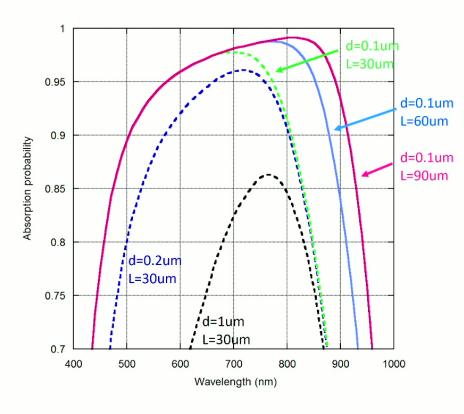
 $P_{trig} \equiv avalanche prob.$ 

Ptrig











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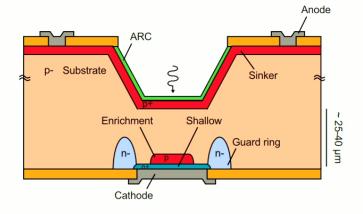
### Two families of Si SPADs:

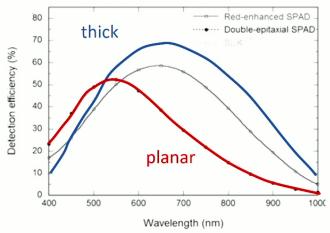
### Thick "Reach-Through" SPAD

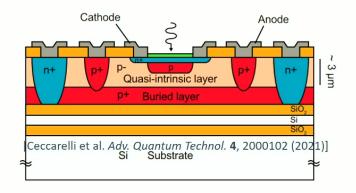
- Processing on both sides of wafer
- Anode and cathode are on opposite sides.
- Thick, high efficiency
- Single element

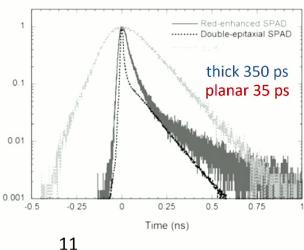
#### Thin "Planar" SPAD

- Processing on top only
- Anode (p<sup>+</sup>) connects w/ sinkers
- Thin
- Back reflector: avoid absorption in deep low field regions
- Suitable for arrays











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## Timing Resolution (Jitter)

Consider a d = 10 um thick absorption region (pretty thick) Optical transit time =  $d \times n/c \approx 14$  fs Carrier transit time =  $d/v_{sat} \approx 10 \text{ ps}$ 

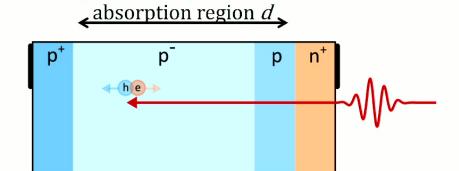
#### Additional jitter from variance in avalanche buildup

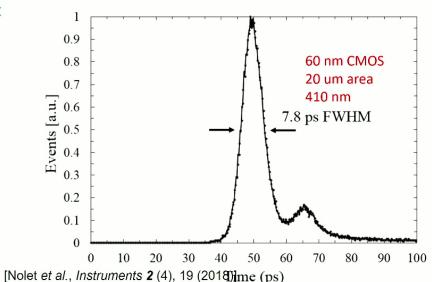
- Perversely, a high ratio of ionization coefficients is better for jitter Other issues that can impact timing resolution:
- junction RC, limiting the slope (dV/dt) of the output current
- readout electronics

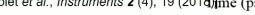
Thick Si SPAD ≈ 150 ps FWHM, 600 ps FW(1%)M

Thin Si planar SPAD ≈ 20 ps to 30 ps FWHM, <400 ps FW(1%)M

CMOS planar SPAD < 20 ps FWHM







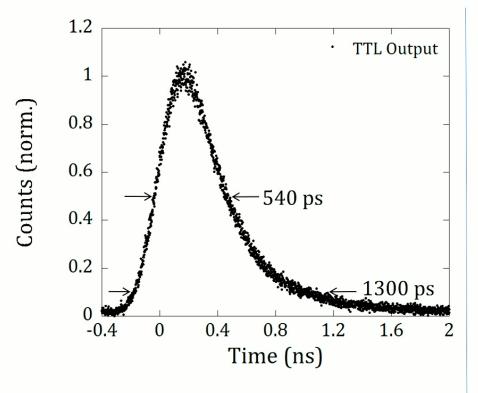
12



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Thick SPAD measured < 350 ps FWHM in lab.

But over FSO link timing resolution degraded significantly.



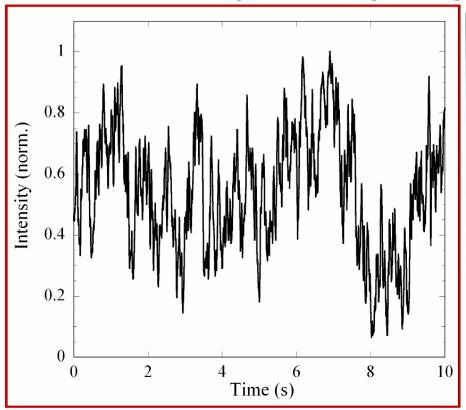
Original temporal resolution insufficient for low-error QKD.



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Thick SPAD measured < 350 ps FWHM in lab.

But over FSO link timing resolution degraded significantly.



Original temporal resolution insufficient for low-error QKD.

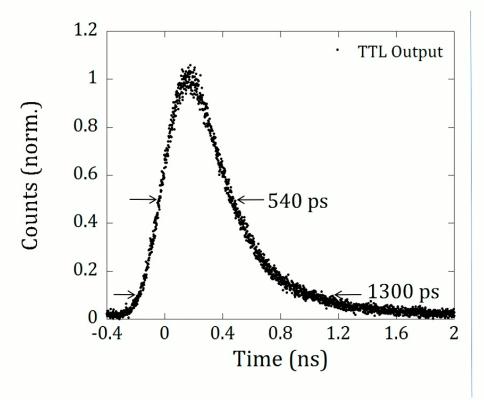
Scintillation-induced **countrate fluctuations** contributed timing jitter.



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Thick SPAD measured < 350 ps FWHM in lab.

But over FSO link timing resolution degraded significantly.



Original temporal resolution insufficient for low-error QKD.

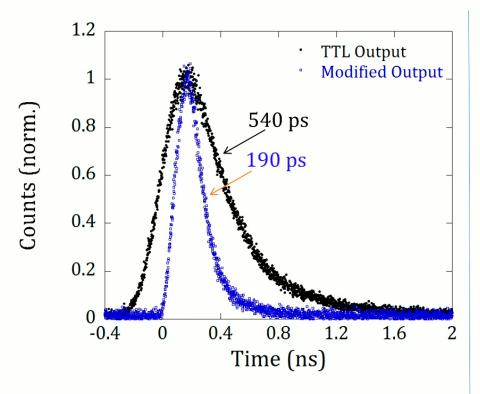
Scintillation-induced **countrate fluctuations** contributed timing jitter.



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Thick SPAD measured < 350 ps FWHM in lab.

But over FSO link timing resolution degraded significantly.



Original temporal resolution insufficient for low-error QKD.

Scintillation-induced **countrate fluctuations** contributed timing jitter.

Detector timing circuitry modified in collaboration with *Politecnico di Milano* 

[I. Rech, *Rev. Sci. Instrum.* 77, 033104-1-5 (2006)]



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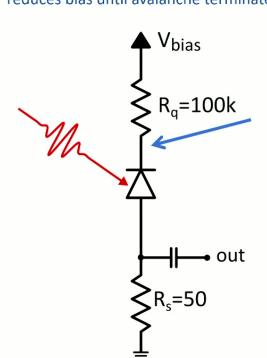
## **Quenching Circuits**

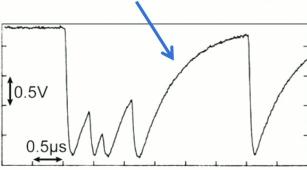
Cathode recharges as R<sub>q</sub>C<sub>d</sub>

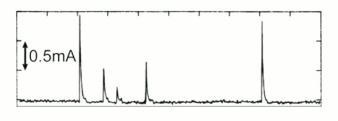
SPADs must operate in a control circuit.

**Passive Quenching** 

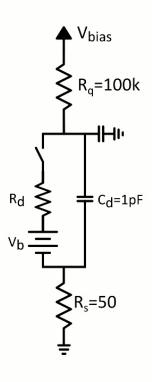
Current through large load resistor drops reduces bias until avalanche terminates







#### Equivalent circuit





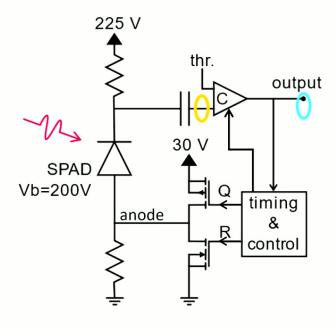
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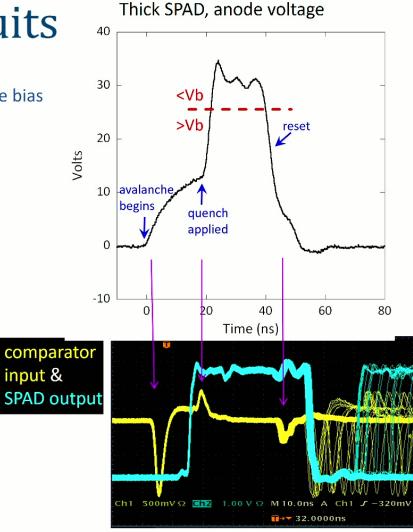
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## **Quenching Circuits**

#### **Active Quenching**

The avalanche is detected and triggers an active feedback to reduce the bias across the SPAD below breakdown, actively terminating the avalanche. This is a vastly higher performance system.





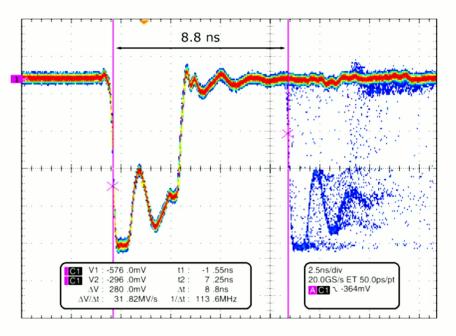


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## **Quenching Circuits**

#### ASICs can greatly improve performance

- Reduced capacitance & faster response times
- Thick SPAD recovery time improved from > 50 ns to < 10 ns</li>



**FIG. 2.** Oscilloscope image of the RT-SPAD timing output (NIM standard) with direct bonding between the device and the AQC. A minimum time interval of 8.8 ns is observed between two subsequent pulses. The measurement has been performed with the same overvoltage (22 V) and the same temperature conditions of the original module.



[Farina et al. Rev. Sci. Instrum. 93, 053102 (2022)]

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# SPAD arrays: SiPM vs. Imaging

SiPM:

- > 10 mm<sup>2</sup> "Silicon Photomultiplier" (SiPM; replacing PMTs)
- · High fill factor
- Avalanche current is additive; quasi-number-resolving
- DCR is sum over all pixels (up to 10<sup>6</sup> s<sup>-1</sup>/mm<sup>2</sup>)

R<sub>s</sub> readout bus Count, TDC Count, TDC AQC AQC AQC

- Actively or passively quenched (AQC drawn here)
- Readout system varies
  - random
  - gated counter (e.g. 10 bit);
  - TDC, or shared TDC
  - both
- 3D single-photon imaging
- Fill factor is issue
- Readout limits size & functionality

NS

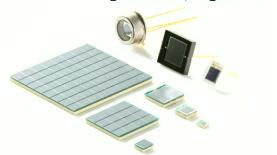
Imaging:

18

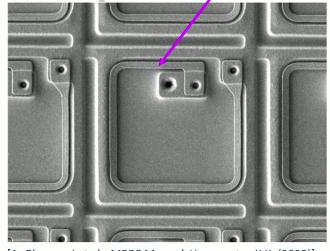
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### SPAD arrays: SiPM

Large format, high fill factor



polysilicon quench resistor

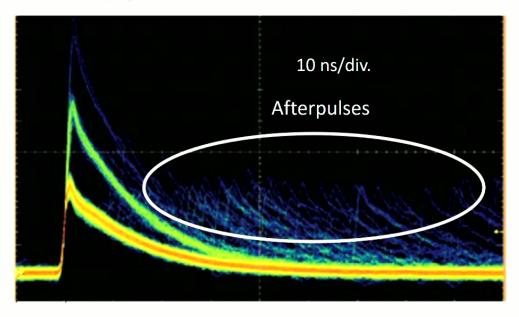


[A. Ghassemi et al., MPPC Manual, Hamamatsu K.K. (2022)]



e-ionization efficiency is higher than h in Si, and red/NIR absorption length is longer

- red/NIR: n-on-p (e- generated deep and travel up to n)
- blue/UV: p-on-n (e-generated shallow and travel down to n)



- Fast edge: typically AC coupled readout
- Low jitter → ToF sensor
- Noise can be discriminated by thresholding on multiple detections
  - pretty high noise *single*-photon detector

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### SPAD arrays: Ganged, ToF sensor



VL53L3CX

VCSEL SiPM

#### Time-of-Flight rar

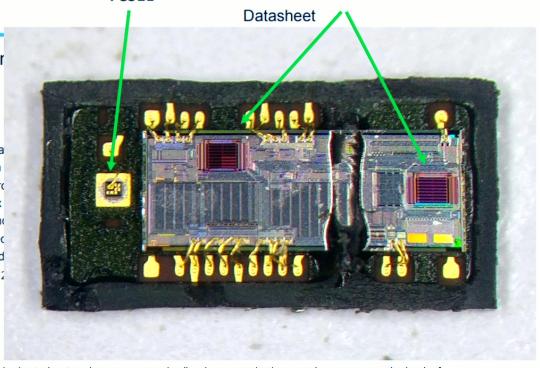


#### **Features**

- Fully integrated minia
  - Emitter: 940 nm
  - Low-power micro
  - Size: 4.4 x 2.4 x
- Fast, accurate distant
  - Histogram based
  - Up to 300 cm+ d

[https://www.st.com/resource/en/datasheet/vl53l3cx.pdf; accessed 2

- < 10 mm range resolution (< 50 ps)</p>
- Probably the least expensive SPAD(s) available



[https://hackaday.io/project/25571-mappydot/log/148243-vl53l1x-teardown; accessed 2/10/23]

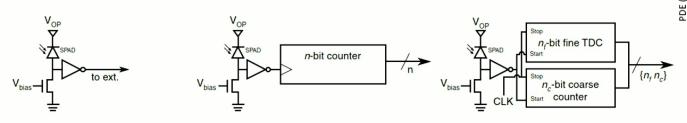


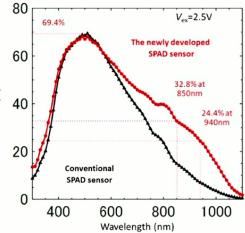
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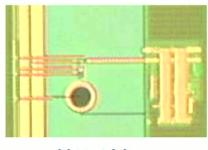
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## SPAD arrays: Imaging

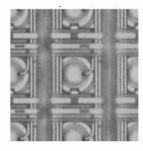
- Imaging SPADs are fabricated in CMOS → D.E. typically max. in the green
- · Readout integration is incorporating more complex systems
- Fill factor



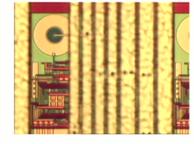








2014, AQC, counter



50 ps AQC, TDC, & counter, 32x32, 2009

[Bruschini et al. Light: Science & Applications 8, 87 (2019)]

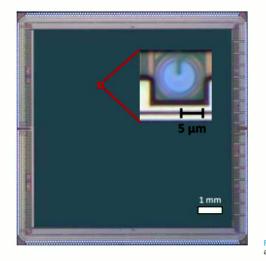


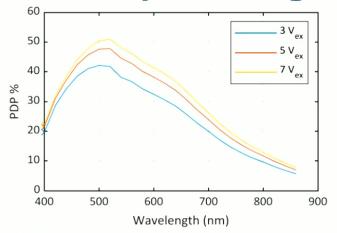
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## SPAD arrays: Imaging

Detailed example: 500 x 500 SPAD imager

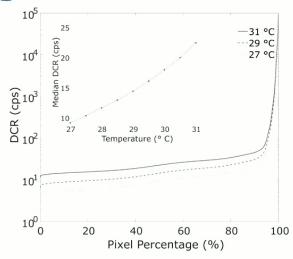
- gated SPADs (1 ns min. gate duration)
- 88 kframes/s readout
- 6 um diameter SPADs, 16.4 um pitch
  - (10.5% fill factor)





0.003	0.010	0.021	0.003	0.001
0.013	0.028	0.050	0.026	0.009
0.018	0.055	100	0.050	0.022
0.007	0.024	0.046	0.026	0.007
0.004	0.004	0.015	0.006	0.002

Fig. 9. SS3 average crosstalk probabilities. The nearest neighbor pixels are below 0.06%, and the nearest diagonal is below 0.03%



[Wayne et al., IEEE Trans. Electron. Dev. 69, 6 (2022)]



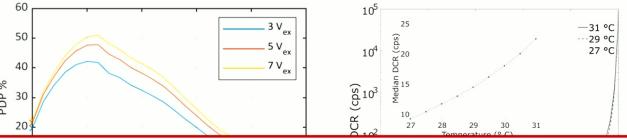
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## SPAD arrays: Imaging

Detailed example: 500 x 500 SPAD imager

- gated SPADs (1 ns min. gate duration)
- 88 kframes/s readout
- 6 um diameter SPADs, 16.4 um pitch
  - (10.5% fill factor)



									7311178 73 7	
	This Work	Ulku 2019 [11]	Morimoto 2020 [8]	Okino 2020 [32]	Dutton 2016 [22]	Parmesan 2015 [26]	Gyongy 2018 [27]	Burri 2014 [10]	Morimoto 2021 [31]	Henderson 2019 [6]
Proc. Tech (nm)	180 CMOS	180 CMOS	180 CMOS	65 CMOS	130 CIS	130 CIS	130 CIS	350 CMOS	90 / 40 3D	90 / 40 3D
Chip Size (mm²)	9.6 x 9.7	9.5 x 9.6	11 x 11	-	3.4 x 3.1	3.5 x 3.1	5 x 5	13.5 x 3.5	-	-
Pixels	500 x 500	512 x 512	1024 x 1000	1200 x 900	320 x 240	256 x 256	256 x 256	512 x 128	2072 x 1548	256 x 256
Pixel Pitch (µm)	16.38	16.38	9.4	6	8	8	16	24	6.39	9.2
Native Fill Factor (%)	10.5	10.5	7.0; 13.4	-	26.8	19.6	61	5	~100	51
Max. PDP (% @ nm)	50 @ 520	50 @ 520	10.5 @ 520 26.7 @ 520	-	39.5 @ 480	-	39.5 @ 480	46 @ 490	69.4 @ 510	23 @ 671
Median DCR (cps / px)	10.2	7.5	0.4; 2.0	-	47	50	6200	366	1.8	20
Max. Frame Rate (kfps)	49.8	97.7	24	0.45	16	4	100	156	0.06	0.76

[Wayne et al., IEEE Trans. Electron. Dev. 69, 6 (2022)]



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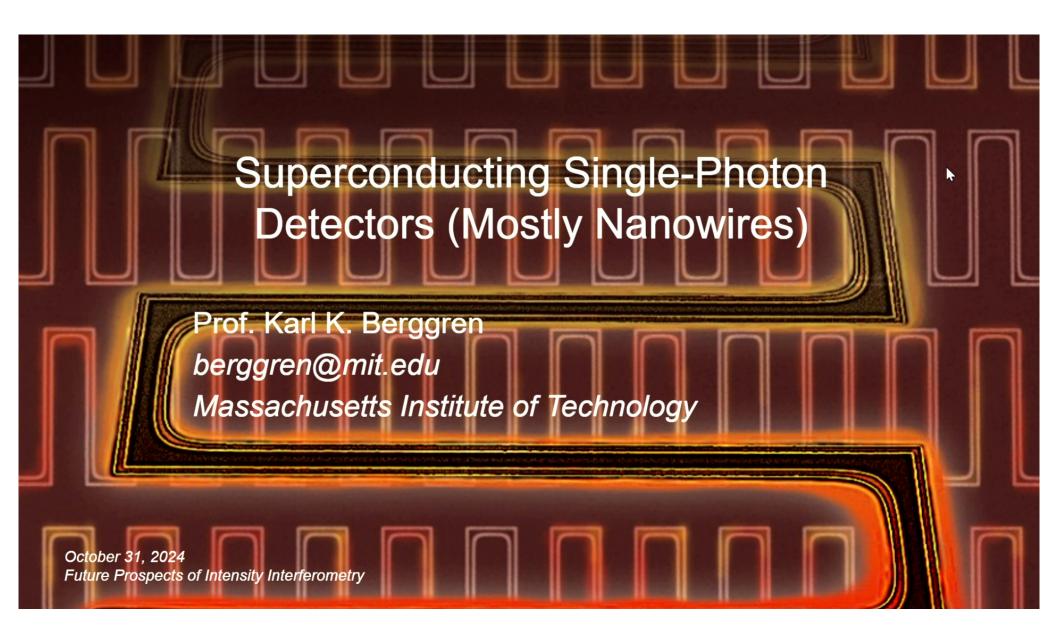
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## Conclusions & Take Aways

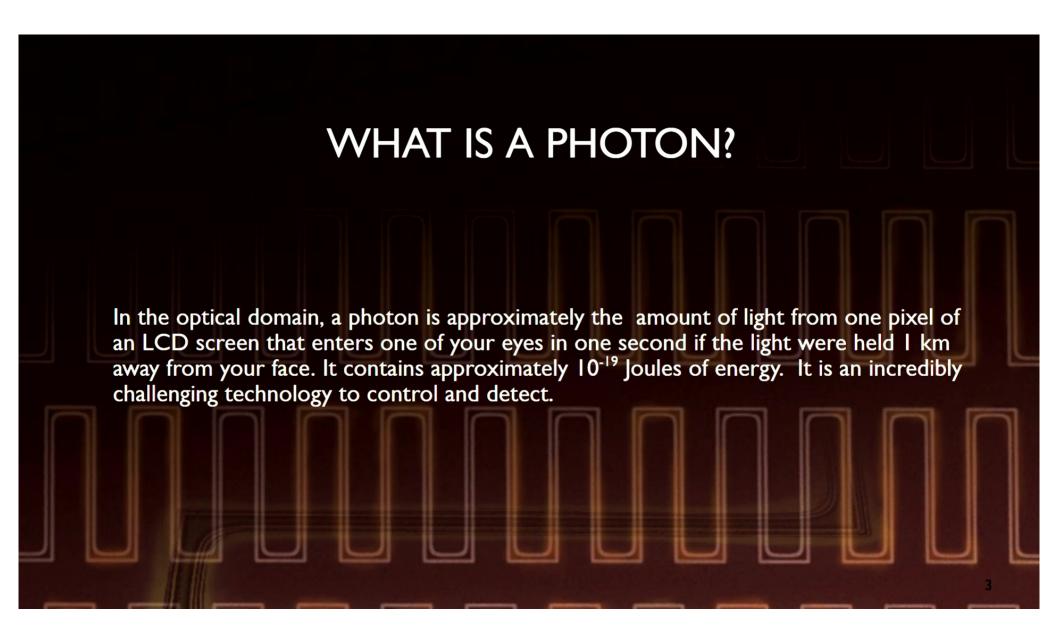
- SPADs are high performance single-photon detectors
  - Not all performance metrics have been achieved in a single device
- Two families of SPADs: thick reach through and thin planar.
- SPADs operate in control circuits that have a significant impact on their performance
- Majority of research in SPADs is in building active arrays (CMOS), improving timing resolution, and developing new materials & devices (e.g. waveguides)



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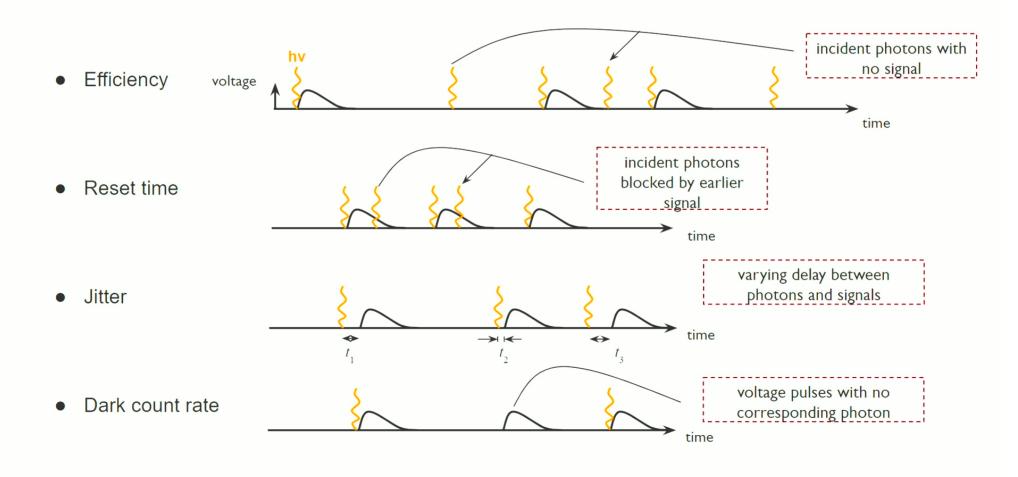


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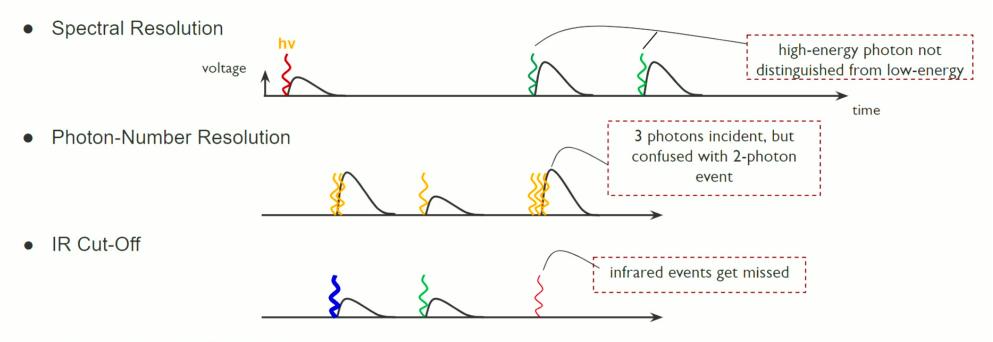
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### Characteristics of Photon Detectors



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### Characteristics of Photon Detectors



- Integration-scale for arrays
- Size, Weight, and Power consumption ("SWaP")

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#### TECHNICAL PAPERS

### THE SECONDARY EMISSION MULTIPLIER—A NEW ELECTRONIC DEVICE\*

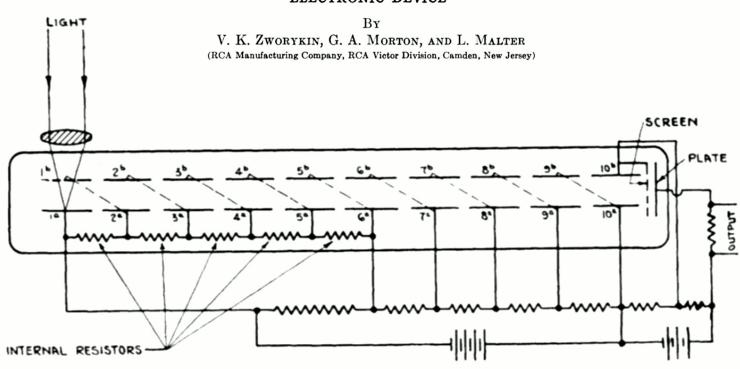
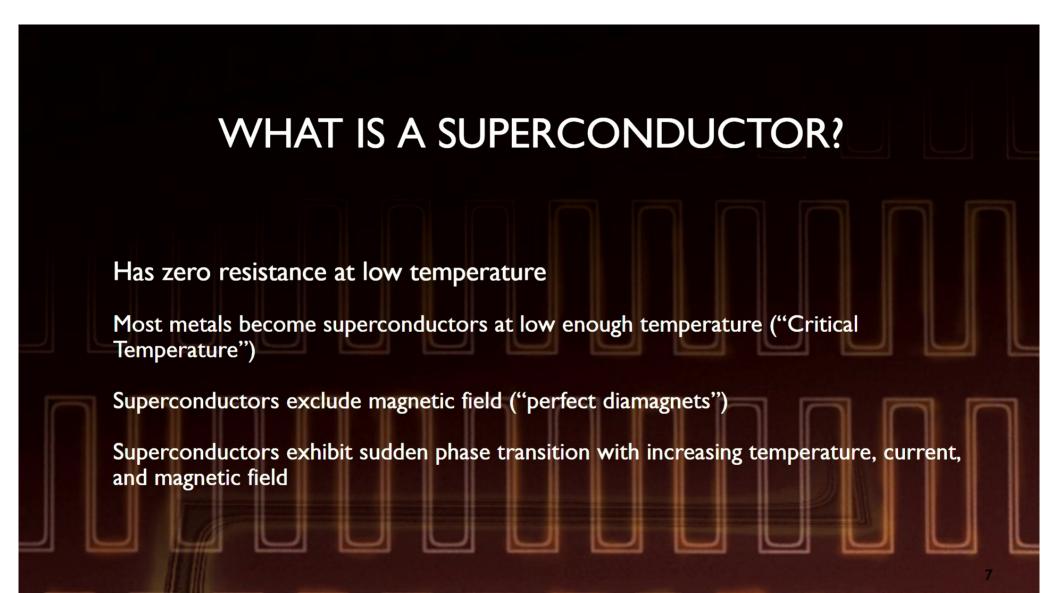


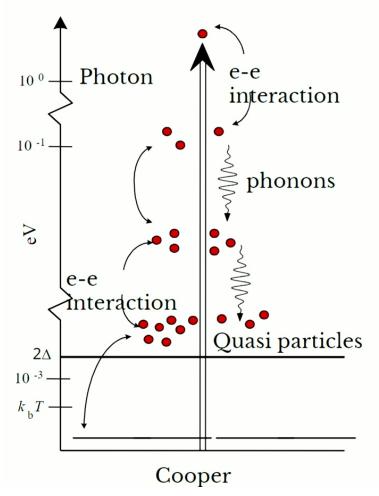
Fig. 9

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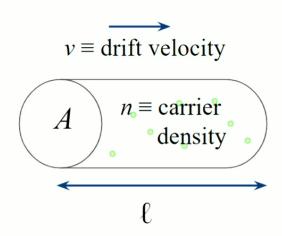
### Band Picture of Superconductor



- Think of it as a semiconductor with a very very small gap (like 1 mV)
- Too many quasiparticles means suppress cooper pair density, and suppress gap

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### **Kinetic Inductors**



Inductive energy  $\equiv$  Kinetic energy

$$\Rightarrow \frac{1}{2} L_{k} i^{2} \equiv \frac{1}{2} M v^{2}$$

$$i = A \cdot n \cdot (2e) \cdot v$$
$$M = \ell \cdot A \cdot m_e \cdot n$$

$$\Rightarrow$$
 inductivity [H · m]  $\equiv \Lambda = m / (n e^2)$ 

https://youtu.be/MAHkYROmriY

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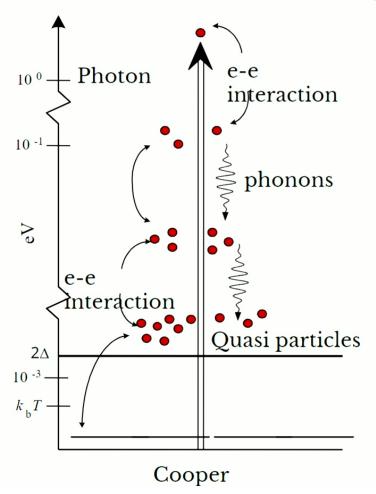
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### Resistive vs. Reactive Response of S/C

- Photons suppress superconductive energy gap and reduce carrier density
  - Reactive response:
    - Inductivity depends inversely on carrier density
    - Inductance increases, causing resonators to shift in frequency and phase
  - Resistive response
    - Phase slips and vortexes are generated
    - Vortex motion generates heat
    - Heat further suppresses superconductivity and resistive regions appear

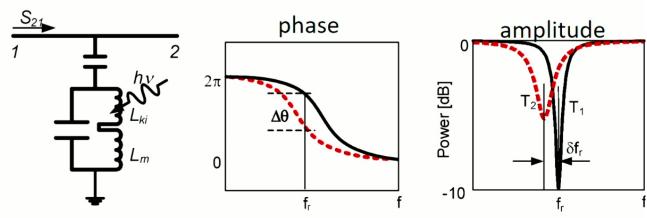
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## MKID: principle of operation



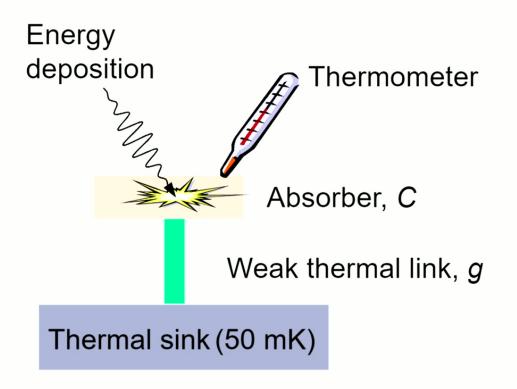
- Microwave Kinetic Inductance Detector
- Measure excess excitations, quasiparticles
- Inductance of a superconducting wire (kinetic inductance) rises in the presence of quasiparticles
- Readout by looking at the change in a resonator

https://doi.org/10.1038/nature02037



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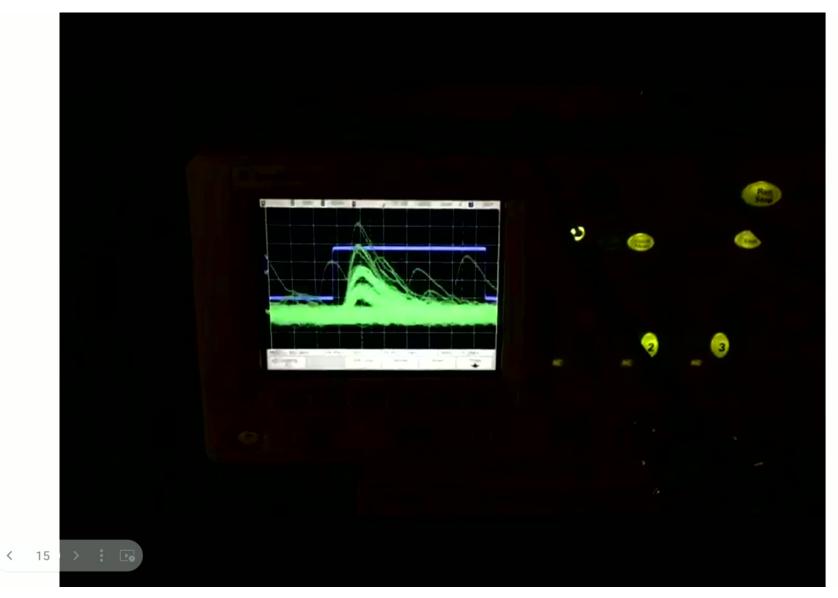
## Transition Edge Sensor (TES)



- Calorimetric detection of UV/optical/IR photons
- Temperatures are ~100 mK
  - low noise
  - high sensitivity.
- NIST Tungsten Superconductor
- AIST Titanium Superconductor

https://doi.org/10.1063/1.113674

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Adriana Lita, NIST

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## History of Superconducting Wire Detectors

Phys. Rev. Lett. **8**, 438 – Published June 1962 SUPERCONDUCTING NUCLEAR PARTICLE DETECTOR

N. K. Sherman

Queen's University, Kingston, Ontario, Canada

#### J. Appl. Phy. 79, 7069 - Published 1996

#### Bolometric and nonbolometric infrared photoresponses in ultrathin superconducting NbN films

M. W. Johnson<sup>a)</sup> and A. M. Herr Department of Physics and Astronomy, University of Rochester, Rochester, New York 14627

Department of Electrical Engineering, University of Rochester, Rochester, New York 14627

#### Appl. Phys. Lett. 6, 79- Published Aug. 2001

#### Picosecond superconducting single-photon optical detector

G. N. Gol'tsman,<sup>a)</sup> O. Okunev, G. Chulkova, A. Lipatov, A. Semenov, K. Smirnov, B. Voronov, and A. Dzardanov *Department of Physics, Moscow State Pedagogical University, Moscow 119435, Russia* 

Department of Physics, Moscow State Fedagogical University, Moscow 119455, Russ

C. Williams and Roman Sobolewski<sup>b)</sup>
Department of Moctrical and Computer Engineering and Laboratory for Laser Energetics,
University of Rochester, Rochester, New York 14627-0231

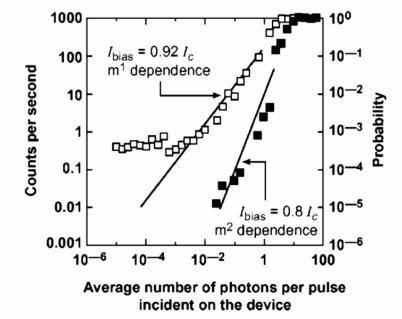
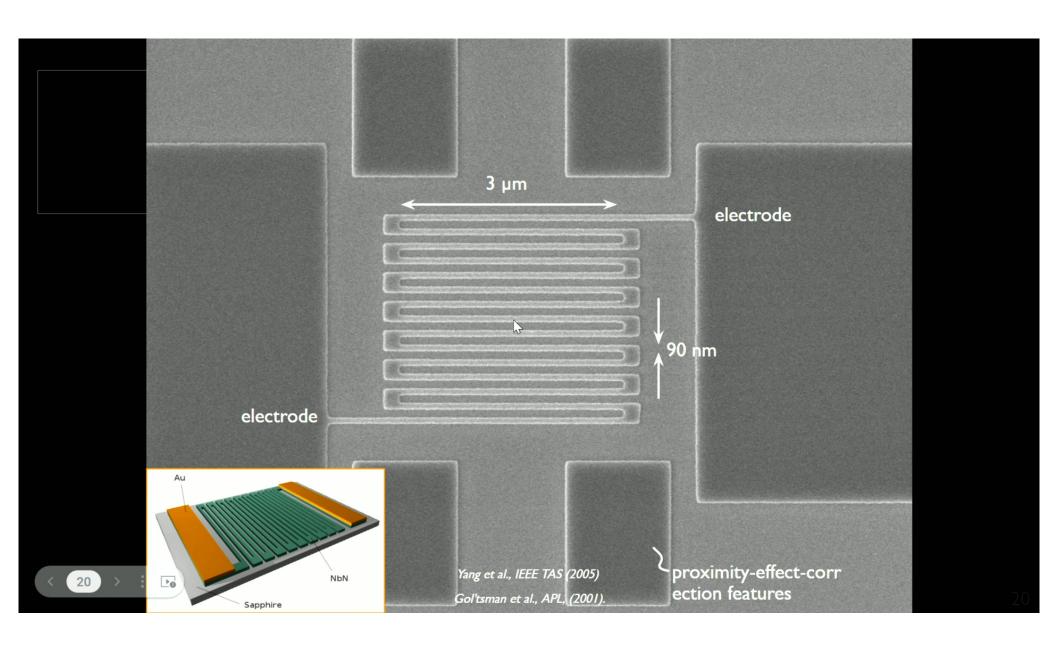


FIG. 3. Number of counts per second recorded by the NbN SPD versus the average number of photons per pulse incident upon the device, for two different bias current levels is shown. The solid lines correspond to the Eq. (4) theoretical predictions. The incident photon wavelength was  $0.81 \mu m$ .

G. N. Gol'tsman et al., "Picosecond superconducting single-photon optical detector," doi: 10.1063/1.1388868.

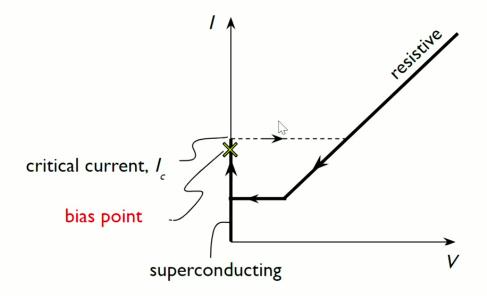
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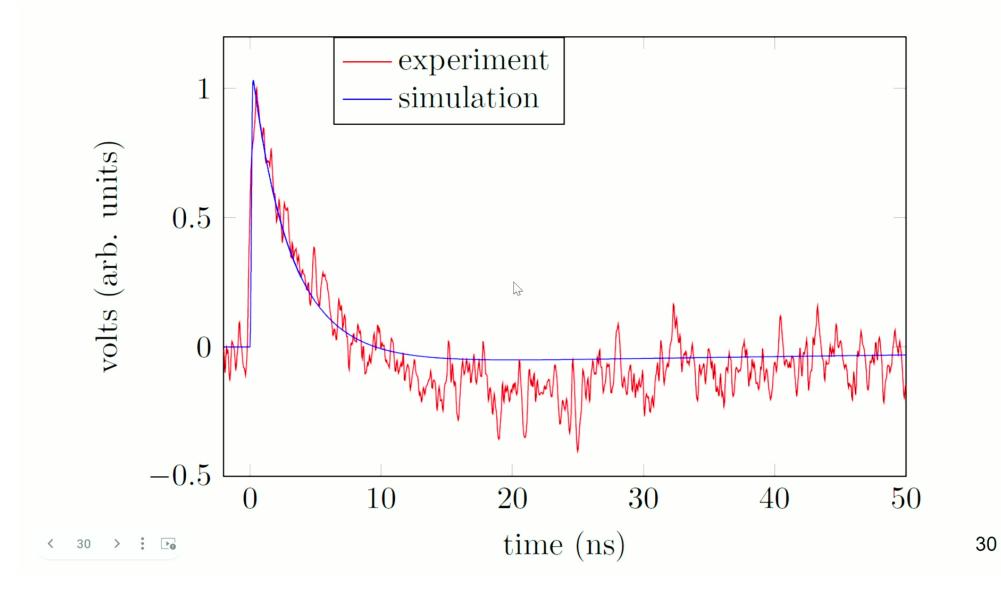
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## Comparison-Based Device



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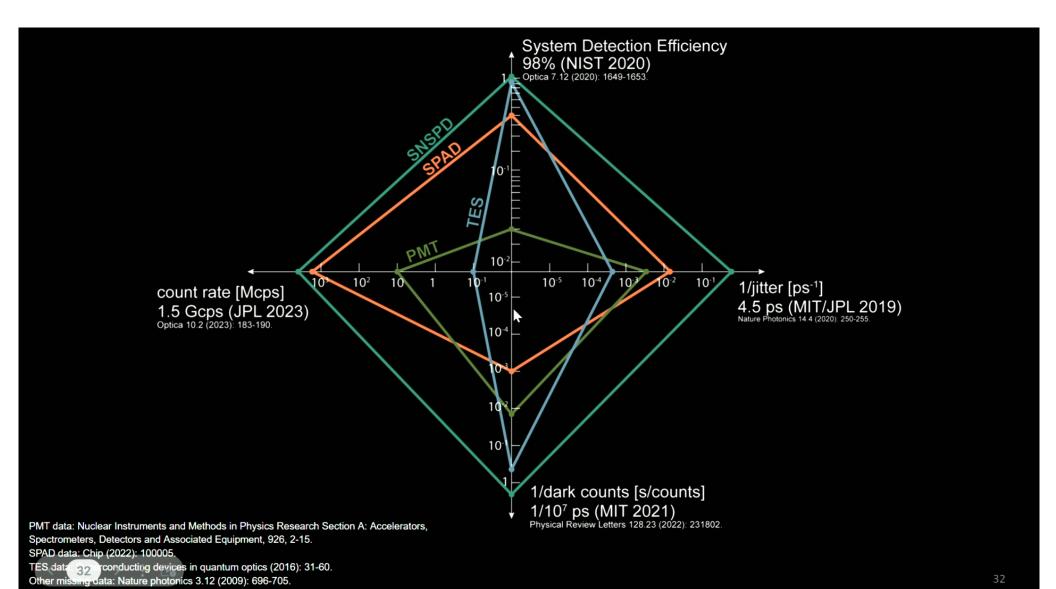
# Why are Superconducting-Nanowire Single-Photon Detectors Special?

- Infrared efficiency for single photons (> 29 μm, JPL/NIST '23)
- Jitter < 3 ps: nothing else can match it for single photons (Korzh+, Nature Photonics 14 '20)
- Efficiency: Competes with transition-edge sensors (98%, Reddy+ CLEO/QELS '19)
- Count rate (~100 Mcps, i.e. 1-10 ns reset)
- Dark-count rate (~ I per day)
- Operates up to 20K, 7 T magnetic fields (Charaev 24, Marvinney 21)
- Convenient fabrication, no shielding, room-temp amplification, relatively higher temperature operation

31

3:

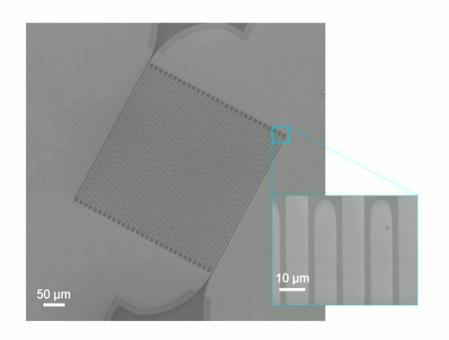
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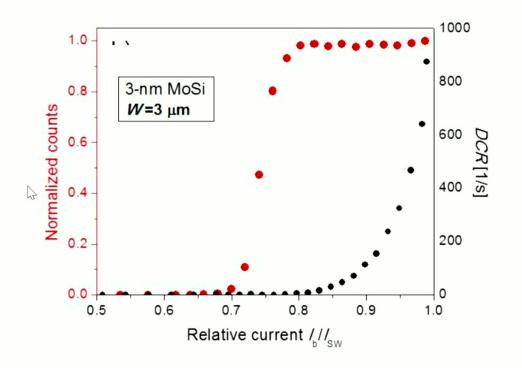


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#### Large-area microwire MoSi single-photon detectors







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Thin 3-nm MoSi film, up to 3  $\mu$ m-wide, operating T = 0.3 K,  $\lambda$  = 1550 nm

1. Charaev et al, Appl. Phys. Lett. 116, 242603 (2020)

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© California, US





Shangai, China

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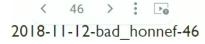
# What Does it Look Like?



Compressor unit fits under optical table.



Cryostat and electronics easily rack mountable.



Copyright © 2017 Quantum Opus, LLC

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## High-order temporal coherences of chaotic and laser light

Martin J. Stevens<sup>1,\*</sup>, Burm Baek<sup>1</sup>, Eric A. Dauler<sup>2,3</sup>, Andrew J. Kerman<sup>3</sup>, Richard J. Molnar<sup>3</sup>, Scott A. Hamilton<sup>3</sup>, Karl K. Berggren<sup>2</sup>, Richard P. Mirin<sup>1</sup> and Sae Woo Nam<sup>1</sup>

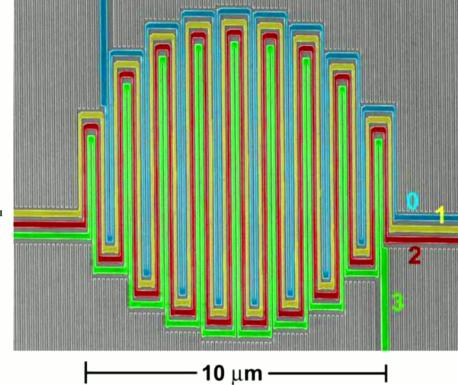


Fig. 1. Scanning-electron microscope image of the four-element SNSPD, with nanowire elements 0-3 traced out in color. Each element consists of a ~5 nm-thick × 80 nm-wide NbN nanowire on a sapphire substrate, with 60 nm gaps between wires. The 9.4 μm-diameter active area is well matched to the spatial mode of a single mode optical fiber, the cleaved end of which is held within ~10 μm of the detector surface. The interleaved design ensures that all four elements equally sample this spatial mode.

2

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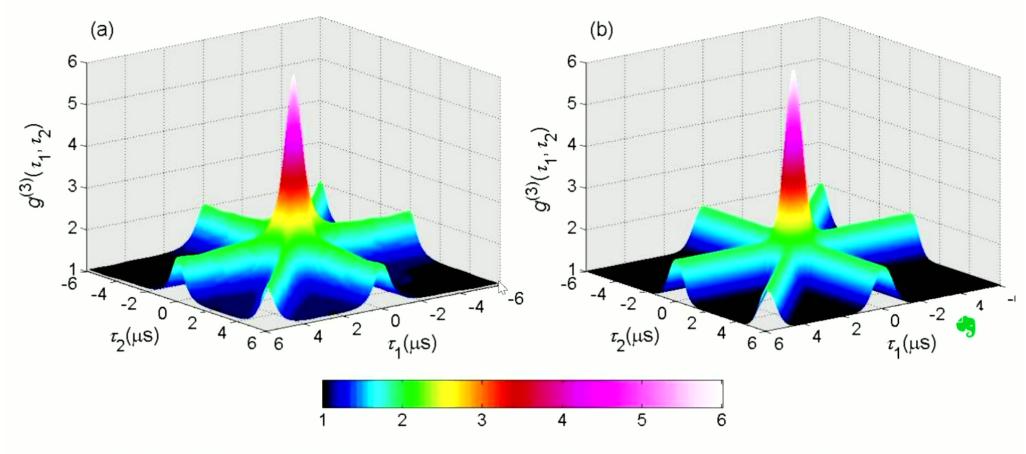
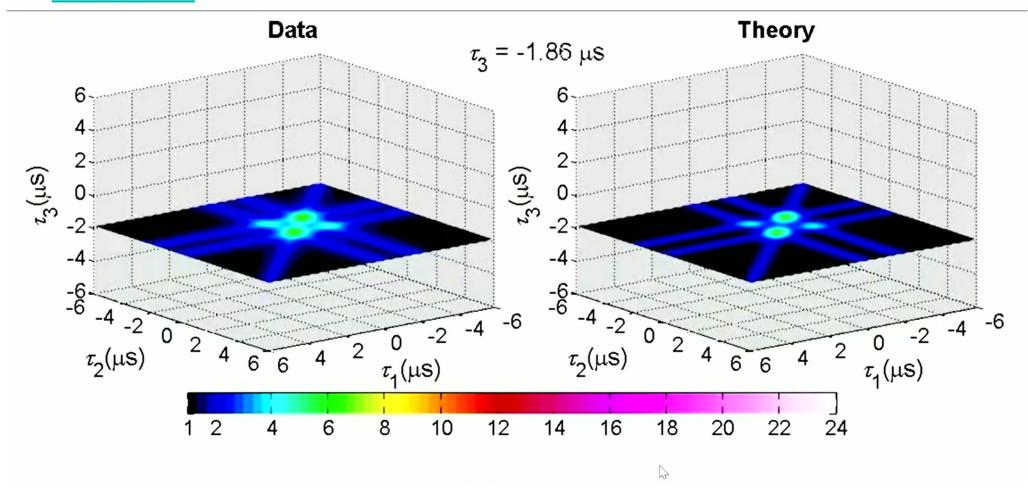


Fig. 3. (a) Measured third-order coherence from the chaotic source, where both color and height indicate measured value of  $g^{(3)}$ . The cross-section in Fig. 2(a) samples these data along a diagonal line (not shown) extending from the far left corner to the far right corner as plotted here—(b) Calculated third-order coherence for a chaotic source derived from an ideal Gaussian scattering process with a coherence time of 900 ns, as discussed in the text.

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#### Link to video



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## Kinetic Inductance: Superconductivity's Ugly Secret

Place for Speaker's video (5cm x 3.5cm)



Specific Inductance  $\equiv L_{\rm S}$ =  $\mu_{\rm o} \frac{\lambda^2}{{\rm Area}}$ 

$$\approx 400 \, \mathrm{pH} \, \mu \mathrm{m}^{-1}$$

Specific Capacitance  $\equiv C_{\rm S}$ 

 $\approx 3.3\epsilon_{\circ}$ 

 $pprox 30\,\mathrm{aF}\,\mu\mathrm{m}^{-1}$ 

G

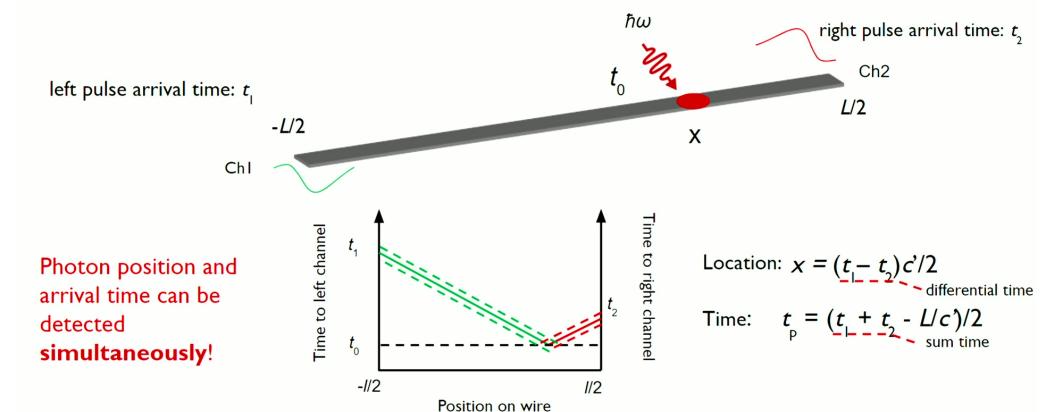
NbN SiO<sub>2</sub> Si Signal Speed =  $c_{\text{eff}}$ =  $\frac{1}{\sqrt{C_{\text{S}}L_{\text{S}}}} \sim \frac{c}{30}$ = 3% c

 $n_{\rm eff} \sim 30$ 

IEEE 2021 Karl Berggre F4: The Superconducting Nanowire as a New Electronic Device

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## Spatial and temporal resolution in a wire

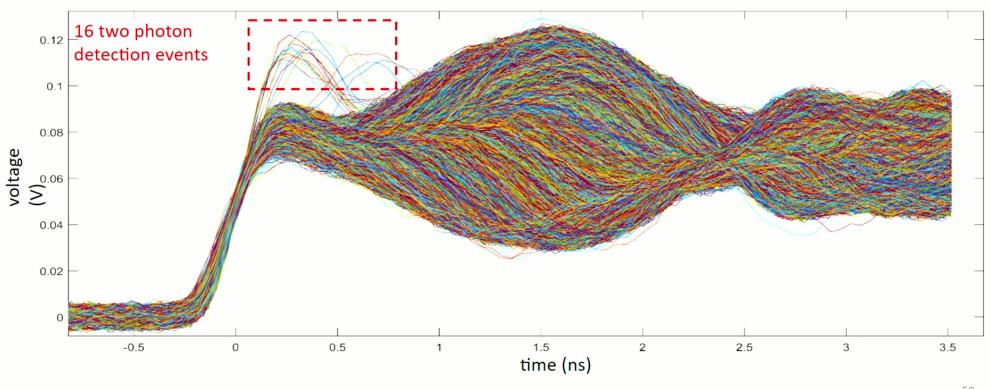


spatial resolution = timing litte

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## Detecting two-photon-firing events

16 two-photon firing events among 50,000 photon detection events (flood illumination over the entire area)



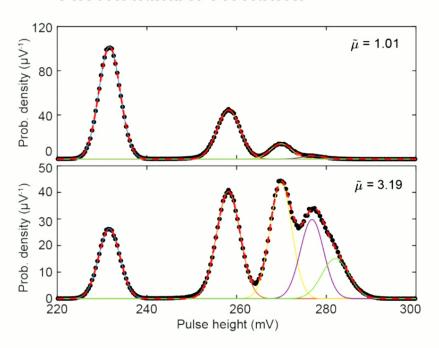
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#### Photon Number Resolution

#### **Jitter reduction**

#### 300 Normalized counts **STaND SNSPD** 0.5 7.4 ps 200 Voltage (mV) 16.1 ps -50 -25 0 50 75 STaND Time delay (ps) 100 Reference **SNSPD** 2 3 1 Time (ns)

#### Photon number resolution



\*Unpublished data

Tapered readout has also enabled:

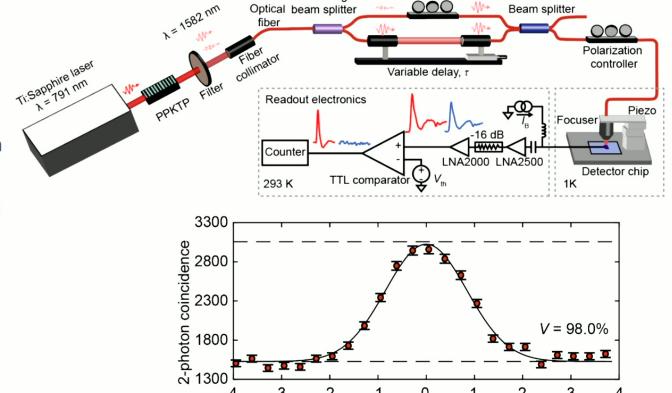
- 1. 25 ps jitter in NbN SNSPD without amplifier (measured at JPL)
- 2. sub-5 ps jitter in WSi using cryogenic amplifiers (Korzh et al. CLEO 2018, paper FW3F.3)

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## Direct measurement of photon bunching in **HOM** interference

Frequency degenerated entangled photon pairs generated through spontaneous parametric down conversion (SPDC) Comparator readout switches the STaND between single-photon-detector and coincidence-counter modes Measured HOM interference visibility of 98%



-2

-3

Polarizing

Polarization controller

0 Relative delay,  $\tau$  (ps) 2

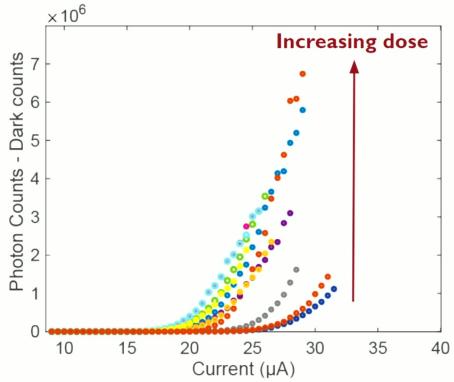
3

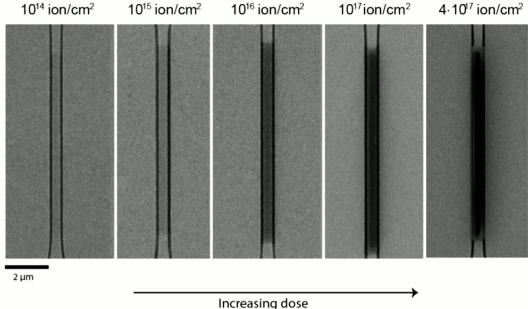
60

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#### Effects of He ion irradiation on NbN SNSPDs

 Demonstration of an improved detection efficiency via defect engineering with He ion irradiation on NbN SNSPDs (first demonstration by Zhang et al., Physical Review Applied, 12(4):044040, 2019)





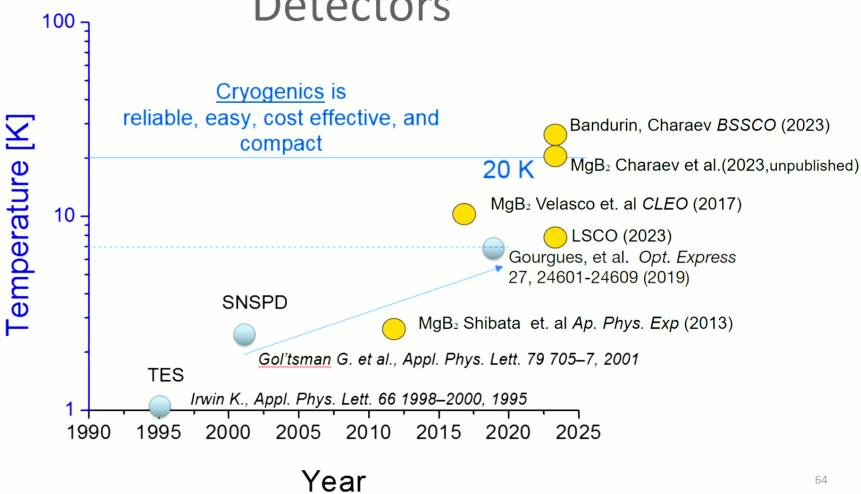
• For doses  $> 5 \cdot 10^{15}$  ions/cm<sup>2</sup>  $\rightarrow$  post processing and enhanced detector metrics

**Detection efficiency**  $\propto$  **Light Counts - Dark Counts** 

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## Operating Temperature of Superconducting Detectors



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#### Thank You!

- To the Perimeter Institute team and the conference organizer
- To the hundreds (thousands?) of Pls, post-docs, students, technicians who have supported this field over decades, and the thousands of administrators/facilities workers/family members who have supported them.
- The major institutions that have been involved in this field include (in random order).
  - O Argonne National Lab, Caltech Jet Propulsion Laboratory, Chalmers University, Delft University of Technology, Eindhoven University of Technology, EPFL, Glasgow University, Heriot Watt University, Italian National Research Council (Rome, Naples)\*, Karlsruhe Institute of Technology, KTH Royal Institute of Technology, Los Alamos National Lab, Michigan State University, MIT Lincoln Laboratory, Moscow State Pedagogical University, Nanjing University, National Institute of Information and Communications Technology (NICT) in Kobe Japan, National Institute of Standards and Technology, Shanghai Institute of Microsystem and Information Technology (SIMIT), SPIN (Naples), The Technion, U. of Naples, U. of Rochester, U. of Salerno, U. of British Columbia, U. of Roma TRE, U. of Waterloo, Yale University, and others that have slipped my mind...

Apologies to anyone I neglected to mention.

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